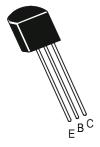
TUV MAAGEMENT SENICE PRINTED



An ISO/TS 16949, ISO 9001 and ISO 14001 Certified Company

NPN SILICON EPITAXIAL TRANSISTOR

CD9581 TO-92 CBE



General Purpose Transistor.

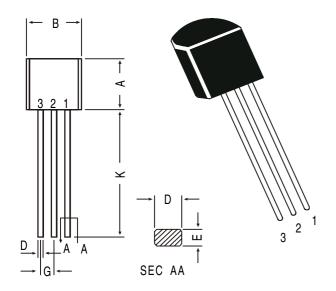
ABSOLUTE MAXIMUM RATINGS(Ta=25deg C)

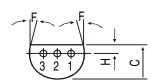
DESCRIPTION	SYMBOL	SYMBOL VALUE		
Collector -Base Voltage	VCBO	60	V	
Collector -Emitter Voltage	VCEO	40	V	
Emitter Base Voltage	VEBO	7.0	V	
Collector Current	IC	100	mA	
Power Dissipation	PD	500	mW	
Operating & Storage Junction	TJ, Tstg	-65 to +125	deg C	
Temperature Range			_	
Lead Temperature for Soldering 1/16"	TL	280	deg C	
From Body, For 10 Seconds			-	
THERMAL RESISTANCE				
Junction to Ambient	Rth(j-a)	200	deg C/W	

ELECTRICAL CHARACTERISTICS (Ta=25 +- 3 deg C Unless Otherwise Specified)

DESCRIPTION	SYMBOL TEST CONDITION		MIN	MAX	UNIT	
Collector -Base Voltage	VCBO	IC=10uA, IE=0	60	-	V	
Collector -Emitter Voltage	VCEO*	IC=1mA, IB=0	40	-	V	
Emitter- Base Voltage	VEBO	EBO IE=100uA, IC=0		-	V	
Collector Cut-off Current	ICBO	VCB=40V, IE=0	-	50	nA	
	ICEO	VCE=35V, IB=0	-	1.0	uA	
Emitter Cut -off Current	IEBO	VEB=7V, IC=0	-	200	nA	
Forward Current Transfer Ratio	hFE	IC=10mA,VCE=10V	150	300		
		IC=100uA,VCE=10V	50	-		
Collector Emitter (Sat) Voltage	VCE(Sat) * IC=50mA,IB=10mA		-	0.22	V	
DYNAMIC CHARACTERISTICS						
Cut off frequency	ft	VCE=5V, IC=10mA	100	350	MHz	
Noise Figure	NF	VCE=5V, IC=12uA	-	12	dB	
		f=1kHz, Rs=k ohm				
Fead Back Capacitance	Cre	VCB=10V, f=1MHz	-	4.0	pF	
Forward Current Transfer Ratio(A.C)	hfe	IC=0.5mA, VCE=5V,	100	-		
		f=50 kHz				
*Pulse test 300us Duty Cycle=2%						

TO-92 Plastic Package



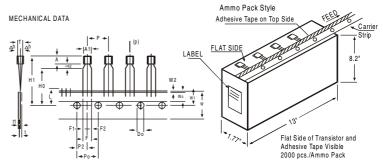


PIN CONFIGURATION

- 1. BASE
- 2. COLLECTOR
- 3. EMITTER

DIM	MIN.	MAX.			
Α	4.32	5.33			
В	4.45	5.20			
С	3.18	4.19			
D	0.41	0.55			
Е	0.35	0.50			
F	5 DEG				
G	1.14	1.40			
Н	1.14	1.53			
K	12.70	_			

TO-92 Transistors on Tape and Ammo Pack



All dimensions in mm unless specified otherwise

ITEM		SPECIFICATION					
IIEW	SYMBOL	MIN.	NOM.	MAX.	TOL.	REMARKS	
BODY WIDTH	A1	4.0		4.8			
BODY HEIGHT	Α	4.8		5.2			
BODY THICKNESS	Т	3.9		4.2			
PITCH OF COMPONENT	Р		12.7		±1		
FEED HOLE PITCH	Po		12.7		±0.3	CUMULATIVE PITCH ERROR 1.0 mm/20 PITCH	
FEED HOLE CENTRE TO COMPONENT CENTRE	P2		6.35		±0.4	TO BE MEASURED AT BOTTOM OF CLINCH	
DISTANCE BETWEEN OUTER					+0.6		
LEADS	F		5.08		-0.2		
COMPONENT ALIGNMENT	Δh		0	1		AT TOP OF BODY	
TAPE WIDTH	W		18		±0.5		
HOLD-DOWN TAPE WIDTH	Wo		6		±0.2		
HOLE POSITION	W1		9		+0.7 -0.5		
HOLD-DOWN TAPE POSITION	W2		0.5		±0.2		
LEAD WIRE CLINCH HEIGHT	Но		16		±0.5		
COMPONENT HEIGHT	H1			23.25			
LENGTH OF SNIPPED LEADS	L			11.0			
FEED HOLE DIAMETER	Do		4		±0.2		
TOTAL TAPE THICKNESS	t			1.2		t1 0.3 - 0.6	
LEAD - TO - LEAD DISTANCEF1,	F2		2.54		+0.4 -0.1		
CLINCH HEIGHT	H2			3	l *		
PULL - OUT FORCE	(P)	6N					

- NOTES

 1. MAXIMUM ALIGNMENT DEVIATION BETWEEN LEADS NOT TO BE GREATER THAN 0.2 mm.

 2. MAXIMUM NON-CUMULATIVE VARIATION BETWEEN TAPE FEED HOLES SHALL NOT EXCEED 1 mm IN 20 PITCHES.
- PITCHES.

 3. HOLDDOWN TAPE NOT TO EXCEED BEYOND THE EDGE(S) OF CARRIER TAPE AND THERE SHALL BE NO EXPOSURE OF ADHESIVE.

 4. NO MORE THAN 3 CONSECUTIVE MISSING COMPONENTS ARE PERMITTED.

 5. A TAPE TRAILER, HAVING AT LEAST THREE FEED HOLES ARE REQUIRED AFTER THE LAST COMPONENT.

 6. SPLICES SHALL NOT INTERFERE WITH THE SPROCKET FEED HOLES.

Packing Detail

PACKAGE	STANDARD PACK		INNER CARTON BOX		OUTER CARTON BOX		
	Details	Net Weight/Qty	Size	Qty	Size	Qty	Gr Wt
l II	1K/polybag 2K/ammo box	g, p	3" x 7.5" x 7.5" 12.5" x 8" x 1.8"	5.0K 2.0K	17" x 15" x 13.5" 17" x 15" x 13.5"	80.0K 32.0K	23 kgs 12.5 kgs

Customer Notes

Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Discrete Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished on the CDIL Web Site/CD is believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Discrete Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

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